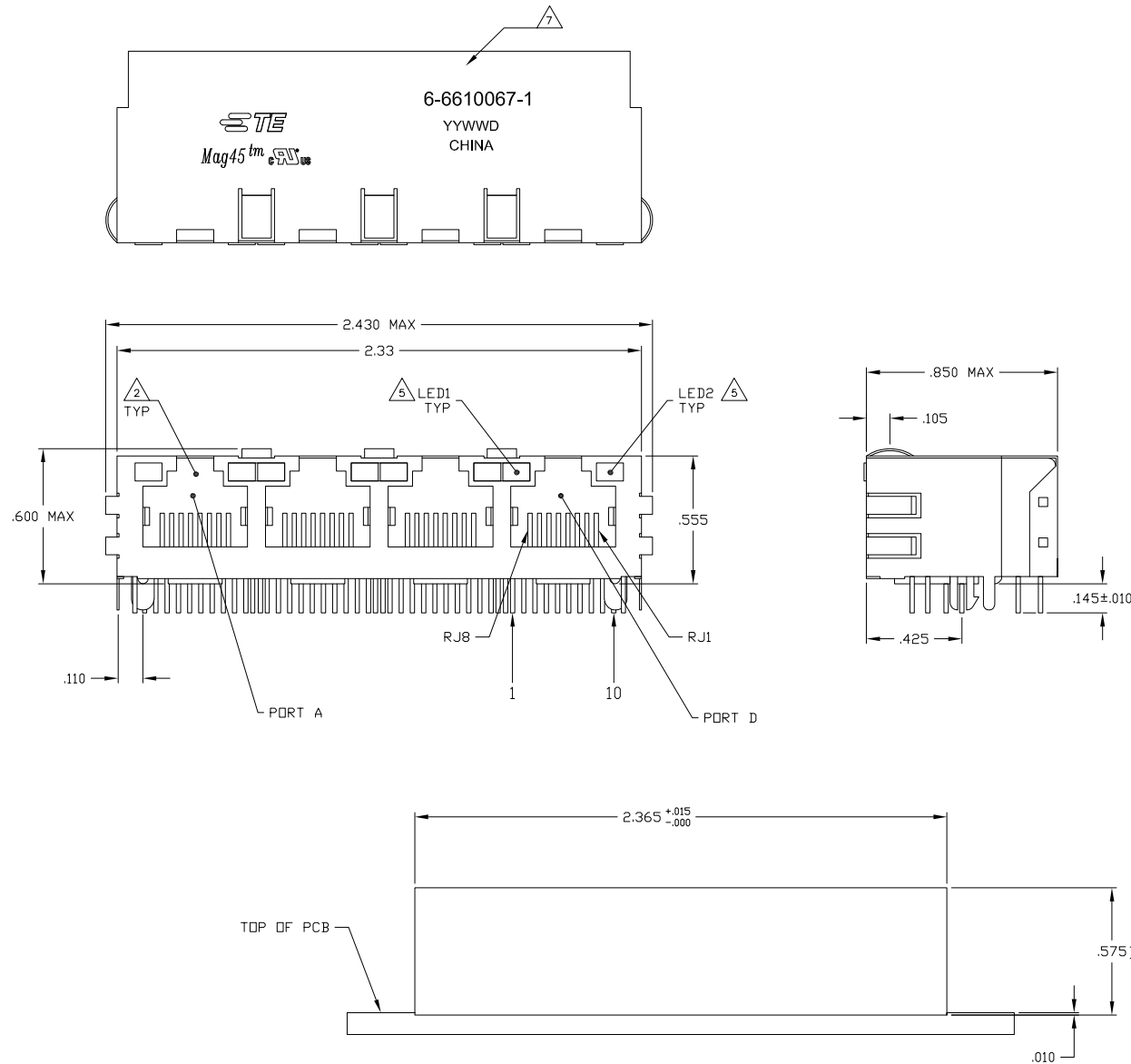


LOC		REV		DATE		BY		APPD	
AA	22	B	REV PER	ECO-08-026409	02SEP2008	VL	TX		
		C	ECO-11-012433		20MAY2011	EL	LR		

MECHANICAL:



1X4 SUGGESTED PANEL CUTOUT

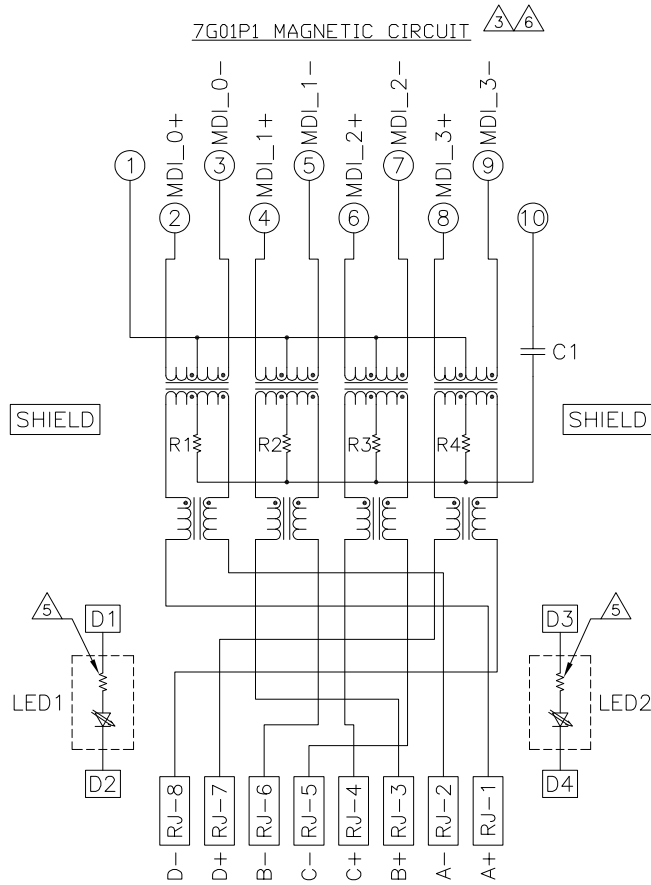
1. MATERIALS:
 - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
3. MAGNETICS
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP-CABLE): 1:1 ALL FOUR PAIRS
 - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100KHZ, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
 - ALL FOUR PAIRS BI-DIRECTIONAL
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
 - 12-20LOG(f/80)dB MIN FROM 4.0.1MHz TO 100MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 - 33-20*LOG(f/50)dB MIN FROM 4.0.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
5. IF THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
 - LED COLOR : DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. ± VF=5V
 - FORWARD CURRENT (IF): GREEN 12 mA TYP. ± VF=5V
6. INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.
7. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

GREEN	GREEN	6-6610067-1
LED1	LED2	PART NUMBER

DIMENSIONS:		DRAWING NO.		DRAWING DATE		DRAWING SCALE		DRAWING SHEET		DRAWING REV	
0 P.L.C.	±	100779	000001	100779	000001	4:1	1	2			
1 P.L.C.	±										
2 P.L.C.	±										
3 P.L.C.	±										
4 P.L.C.	±										
ANGLES	±										
MATERIAL											
FINISH											
CUSTOMER DRAWING		SCALE		SHEET		REV		C			

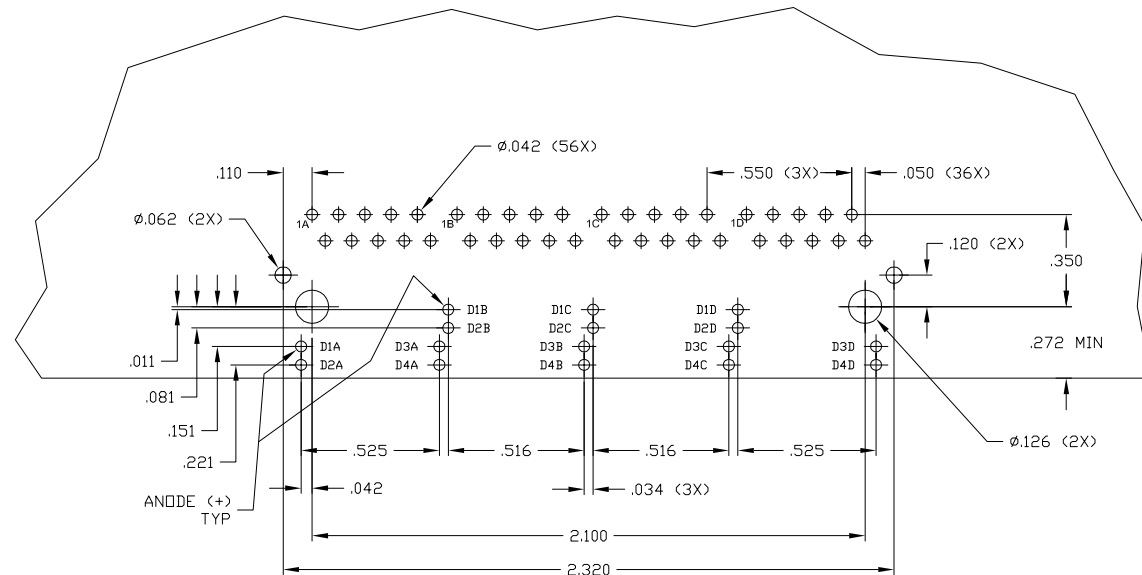
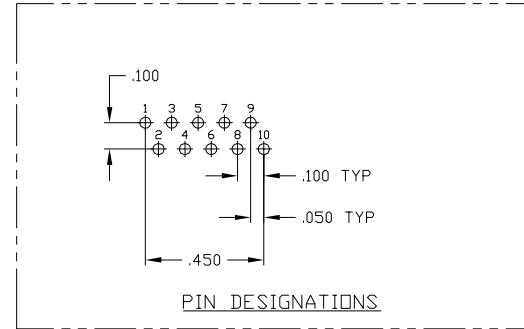
ELECTRICAL:

7G01P1 MAGNETIC CIRCUIT



C1 = 1000 pF, 2kV CAPACITOR

R1-R4 = 75 OHMS, 1/16W RESISTORS



SUGGESTED PCB LAYOUT
 (Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	1	DATE	17MAR2008	TE Connectivity
DRAWN BY: J. VARELA		CHK	5	DATE	17MAR2008	
DESIGNED BY: D. FAROLE		APP	1	DATE	17MAR2008	1X4 MAG45(TM) MODULAR JACK, 7G01P1 SCHEMATIC, (10 PIN HORIZONTAL), 7G01P1 MAGNETIC CIRCUIT, DECOUPLING CAPACITOR, WITH RESISTOR LEADS
DIMENSIONS: INCHES		PRODUCT SPEC	108-2100			
0 P.L.C. ± .010		APPLICATION SPEC	108-2100			
1 P.L.C. ± .008		SIZE	A1	00779	C=6610067	
2 P.L.C. ± .006		WEIGHT	-			
3 P.L.C. ± .005		MATERIAL	-			
4 P.L.C. ± .004		FINISH	-			
5 P.L.C. ± .003		CUSTOMER DRAWING	-			
6 P.L.C. ± .002		SCALE	4:1			
7 P.L.C. ± .001		SHEET	2 of 2			
8 P.L.C. ± .000		REV	C			